

Electronic Patent Application Fee Transmittal

Application Number:	10718192
Filing Date:	20-Nov-2003
Title of Invention:	Heat spreader ball grid array (HSBGA) design for low-k integrated circuits (IC)
First Named Inventor:	Yian-Liang Kuo
Filer:	Daniel R. McClure
Attorney Docket Number:	TS03-336

Filed as Large Entity

Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 1 month with \$0 paid	1251	1	120	120

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				120